

IN THE SPECIFICATION

Please replace the paragraph beginning at page 35, line 1, with the following paragraph:

Final structure release is accomplished on the wafer topside in Figure 9K using dry etching, which punctures through the trenches 916 to suspend the movable elements of the mirror ~~924~~913 and the frame ~~925~~927. In addition, the release etch promotes electrical isolation by separating, for example, the silicon of the frame 927 from the silicon of surrounding members 928 and 920. The vias 909 serve to connect the regions of silicon to the metal interconnects 911. To completely seal the mirrors from the outside environment, a lid wafer 930 is bonded to the device wafer 920, preferably through the frit glass seal 931. The lid wafer 930 is typically glass to allow incoming light to be transmitted with low loss in the mirror cavity 932, reflect off of the mirror surface 913, and transmit out of the mirror cavity.